

Title (en)

COPPER ALLOY AND METHOD FOR PRODUCING COPPER ALLOY

Title (de)

KUPFERLEGIERUNG UND HERSTELLUNGSVERFAHREN FÜR DIE KUPFERLEGIERUNG

Title (fr)

ALLIAGE DE CUIVRE ET PROCÉDÉ DE FABRICATION DE CELUI-CI

Publication

EP 2653574 B1 20170531 (EN)

Application

EP 11848127 A 20111213

Priority

- JP 2010276607 A 20101213
- JP 2011078786 W 20111213

Abstract (en)

[origin: EP2653574A1] To provide a copper alloy of the FCC structure containing Ni: 3.0 to 29. mass%, Al: 0.5 to 7.0 mass%, and Si: 0.1 to 1.5 mass%, with the remainder consisting of Cu and incidental impurities, wherein the copper alloy is of the high strength, but is excellent in workability, and has high electrical conductivity, and can control property thereof, by precipitating a 3rd phase of the L1 2 structure including Si at an average particle diameter of 100 nm or less in a parent phase of the copper alloy.

IPC 8 full level

C22C 9/06 (2006.01); **C22C 9/01** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP KR US)

C22C 9/00 (2013.01 - KR); **C22C 9/01** (2013.01 - EP KR US); **C22C 9/02** (2013.01 - US); **C22C 9/04** (2013.01 - US); **C22C 9/05** (2013.01 - US); **C22C 9/06** (2013.01 - EP KR US); **C22F 1/08** (2013.01 - EP KR US); **H01B 1/026** (2013.01 - EP US)

Cited by

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DOCDB simple family (publication)

EP 2653574 A1 20131023; **EP 2653574 A4 20140910**; **EP 2653574 B1 20170531**; CN 103328665 A 20130925; CN 103328665 B 20160413; JP 5743165 B2 20150701; JP WO2012081573 A1 20140522; KR 101576715 B1 20151210; KR 20130089661 A 20130812; US 2013333812 A1 20131219; WO 2012081573 A1 20120621

DOCDB simple family (application)

EP 11848127 A 20111213; CN 201180059926 A 20111213; JP 2011078786 W 20111213; JP 2012548789 A 20111213; KR 20137015270 A 20111213; US 201113993642 A 20111213